

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

SECURITY AGREEMENT

CONVEYING PARTY DATA

Name	Execution Date
AMKOR TECHNOLOGY, INC.	02/10/2006

RECEIVING PARTY DATA

Name:	Bank of America, N.A.
Street Address:	901 Main Street
Internal Address:	22nd Floor
City:	Dallas
State/Country:	TEXAS
Postal Code:	75202

PROPERTY NUMBERS Total: 18

Property Type	Number
Patent Number:	6982488
Patent Number:	6982485
Patent Number:	6977431
Patent Number:	6967395
Patent Number:	6967124
Patent Number:	6965159
Patent Number:	6965157
Patent Number:	6963141
Patent Number:	6962829
Patent Number:	6956201
Patent Number:	6953988
Patent Number:	6984879
Patent Number:	6990226
Application Number:	10884082

PATENT

500081303

REEL: 017215 FRAME: 0953

CH \$720.00 6982488

Application Number:	10803333
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Application Number:	10785528
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Application Number:	10227051
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Application Number:	10156889
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#### CORRESPONDENCE DATA

Fax Number: (214)855-4300

*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*

Phone: 2148554775

Email: awalker@jenkens.com

Correspondent Name: Andrea Walker

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Address Line 2: Suite 3700

Address Line 4: Dallas, TEXAS 75202-2799

ATTORNEY DOCKET NUMBER:	46715-1296 AMKOR PATENT
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NAME OF SUBMITTER:	ANDREA WALKER
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#### Total Attachments: 7

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## PATENT SECURITY AGREEMENT

(Amkor Technology, Inc.)

THIS PATENT SECURITY AGREEMENT ("Agreement") is between AMKOR TECHNOLOGY, INC., a Delaware corporation (the "Debtor"), and BANK OF AMERICA, N.A., a national banking association (the "Secured Party"), acting in its capacity as administrative agent pursuant to that certain Loan and Security Agreement dated as of November 28, 2005 (as amended, restated, or otherwise modified, the "Loan and Security Agreement") among Debtor, its Subsidiaries party thereto, the lending institutions party thereto and the Secured Party (capitalized terms defined by the Loan and Security Agreement wherever used in this Agreement, unless otherwise defined in this Agreement, shall have the meanings specified in the Loan and Security Agreement).

### RECITALS:

A. Pursuant to the terms of the Loan and Security Agreement, the Debtor has granted to the Secured Party a lien and security interest in all General Intangibles of the Debtor including, without limitation, all of the Debtor's right, title, and interest in, to, and under all now owned and hereafter acquired Patents (as defined below) and Patent Licenses (as defined below), and all products and proceeds thereof, to secure the payment of the Obligations.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the Debtor hereby grants to the Secured Party a lien and continuing security interest in all of the Debtor's right, title, and interest in, to, and under the following (all of the following items or types of property being herein collectively referred to as the "Patent Collateral"), whether presently existing or hereafter created or acquired:

(1) each patent (the "Patent") and each application for a Patent ("Patent Application"), including, without limitation, each Patent and Patent Application referred to in Schedule 1 annexed hereto, together with any reissues, continuations, divisions, modifications, substitutions, or extensions thereof;

(2) each Patent License, to the extent allowable under the license agreement, including, without limitation, each Patent License referred to in Schedule 1 annexed hereto; and

(3) all products and proceeds of the foregoing, including, without limitation, any claim by the Debtor against third parties for past, present, or future infringement or breach of any Patent or Patent License, including, without limitation, any Patent or Patent License referred to in Schedule 1 annexed hereto, and any Patent issued pursuant to a Patent Application referred to in Schedule 1 annexed hereto.


The lien and security interest contained in this Agreement is granted in conjunction with the liens and security interests granted to the Secured Party pursuant to the Loan and Security Agreement.

The Debtor hereby acknowledges and affirms that the rights and remedies of the Secured Party with respect to the liens and security interests in the Patent Collateral made and granted hereby are more fully set forth in the Loan and Security Agreement, the terms and provisions of which are incorporated by reference herein as if fully set forth herein.

IN WITNESS WHEREOF, the Debtor has caused this Agreement to be duly executed by its duly authorized officer as of the 10<sup>th</sup> day of February, 2006.

DEBTOR:

AMKOR TECHNOLOGY, INC.

By:   
Name: Kenneth T. Joyce  
Title: Executive Vice President

SECURED PARTY:

BANK OF AMERICA, N.A.

By: \_\_\_\_\_  
Name: Joy L. Bartholomew  
Title: Senior Vice President

IN WITNESS WHEREOF, the Debtor has caused this Agreement to be duly executed by its duly authorized officer as of the 10<sup>th</sup> day of February, 2006.

DEBTOR:

AMKOR TECHNOLOGY, INC.

By: \_\_\_\_\_  
Name: \_\_\_\_\_  
Title: \_\_\_\_\_

SECURED PARTY:

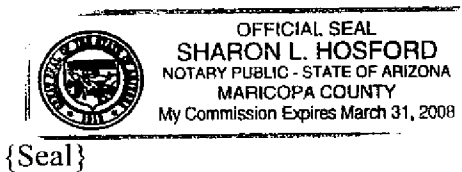
BANK OF AMERICA, N.A.

By: J. L. Bartholomew  
Name: Joy L. Bartholomew  
Title: Senior Vice President

ACKNOWLEDGMENT

STATE OF ARIZONA                     )  
   )  
COUNTY OF MARICOPA                )

This instrument was acknowledged before me this <sup>et</sup> 10 day of February, 2006, by Kenneth T. Joyce, as Executive Vice President of Amkor Technology, Inc., a Delaware corporation, on behalf of such corporation.



Sharon L. Hosford  
Notary Public in and for the State of Arizona

My commission expires: March 31, 2008

STATE OF TEXAS                     )  
   )  
COUNTY OF DALLAS                )

This instrument was acknowledged before me this \_\_\_ day of February, 2006, by Joy L. Bartholomew, as Senior Vice President of Bank of America, N.A., a national banking association, on behalf of such banking association.

{Seal}

\_\_\_\_\_  
Notary Public in and for the State of Texas

My commission expires: \_\_\_\_\_

ACKNOWLEDGMENT

STATE OF ARIZONA )

COUNTY OF \_\_\_\_\_ )

This instrument was acknowledged before me this \_\_\_\_ day of February, 2006, by \_\_\_\_\_, as \_\_\_\_\_ of Amkor Technology, Inc., a Delaware corporation, on behalf of such corporation.

{Seal}

\_\_\_\_\_  
Notary Public in and for the State of Arizona

My commission expires: \_\_\_\_\_

STATE OF TEXAS )

COUNTY OF DALLAS )

This instrument was acknowledged before me this 21<sup>st</sup> day of February, 2006, by Joy L. Bartholomew, as Senior Vice President of Bank of America, N.A., a national banking association, on behalf of such banking association

{Seal}

Margaret A. Henderson  
Notary Public in and for the State of Texas

My commission expires: \_\_\_\_\_



Schedule 1  
to  
Patent Security Agreement

SCHEDULE 1

DALLAS2 1141235v2 46715-01296

**PATENT**  
**REEL: 017215 FRAME: 0960**

**Amkor Technology, Inc.  
U.S. Patents**

#	USPN / Application No.	Issued / Filing Date	Title	Status
393	6,982,488	01/30/2006	Semiconductor package and method for fabricating the same	Issued
394	6,982,485	01/03/2006	Stacking structure for semiconductor chips and a semiconductor package using it	Issued
395	6,977,431	12/20/2005	Stackable semiconductor package and manufacturing method thereof	Issued
396	6,967,395	11/22/2005	Mounting for a package containing a chip	Issued
397	6,967,124	11/22/2005	Imprinted integrated circuit substrate and method for imprinting an integrated circuit substrate	Issued
398	6,965,159	11/15/2005	Reinforced lead-frame assembly for interconnecting circuits within a circuit module	Issued
399	6,965,157	11/15/2005	Semiconductor package with exposed die pad and body-locking lead frame	Issued
400	6,963,141	11/08/2005	Semiconductor package for efficient heat spreading	Issued
401	6,962,829	11/08/2005	Method of making near chip size integrated circuit package	Issued
402	6,956,201	10/18/2005	Image sensor package fabrication method	Issued
403	6,953,988	10/11/2005	Semiconductor package	Issued
404	2004884082	07/01/2004	Substrate for semiconductor package wire bonding method using thereof	Pending
405	2004803333	03/17/2004	Stackable semiconductor package having semiconductor chip within central through hole of substrate	Pending
406	2004785528	02/24/2004	Semiconductor package and method for fabricating the same	Pending
407	2002227051	08/23/2002	Optic semiconductor module and manufacturing method	Pending
408	2002156889	05/30/2002	Method of making an integrated circuit package	Pending
409	6,984,879	01/10/2006	Clamp for pattern recognition	Issued
410	6,990,226	01/24/2006	Pattern recognition method	Issued